

OL-SA58635UK

Wafer level chip-size package; 16 balls; 1.7 x 1.7 x 0.56 mm

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	WLCSP
Package type industry code	WLCSP
Package style descriptive code	UC (uncased chip)
Package style suffix code	NA (not applicable)
Package body material type	X (other)
Mounting method type	S (surface mount)
Issue date	19-1-2010

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	1.67	-	1.7	1.73	mm
E	package width	1.67	-	1.7	1.73	mm
A	seated height	0.51	-	0.56	0.62	mm
A ₂	package height	0.34	-	0.36	0.39	mm
e	nominal pitch	-	-	0.4	-	mm
n ₂	actual quantity of termination	-	-	16	-	



2. Package outline

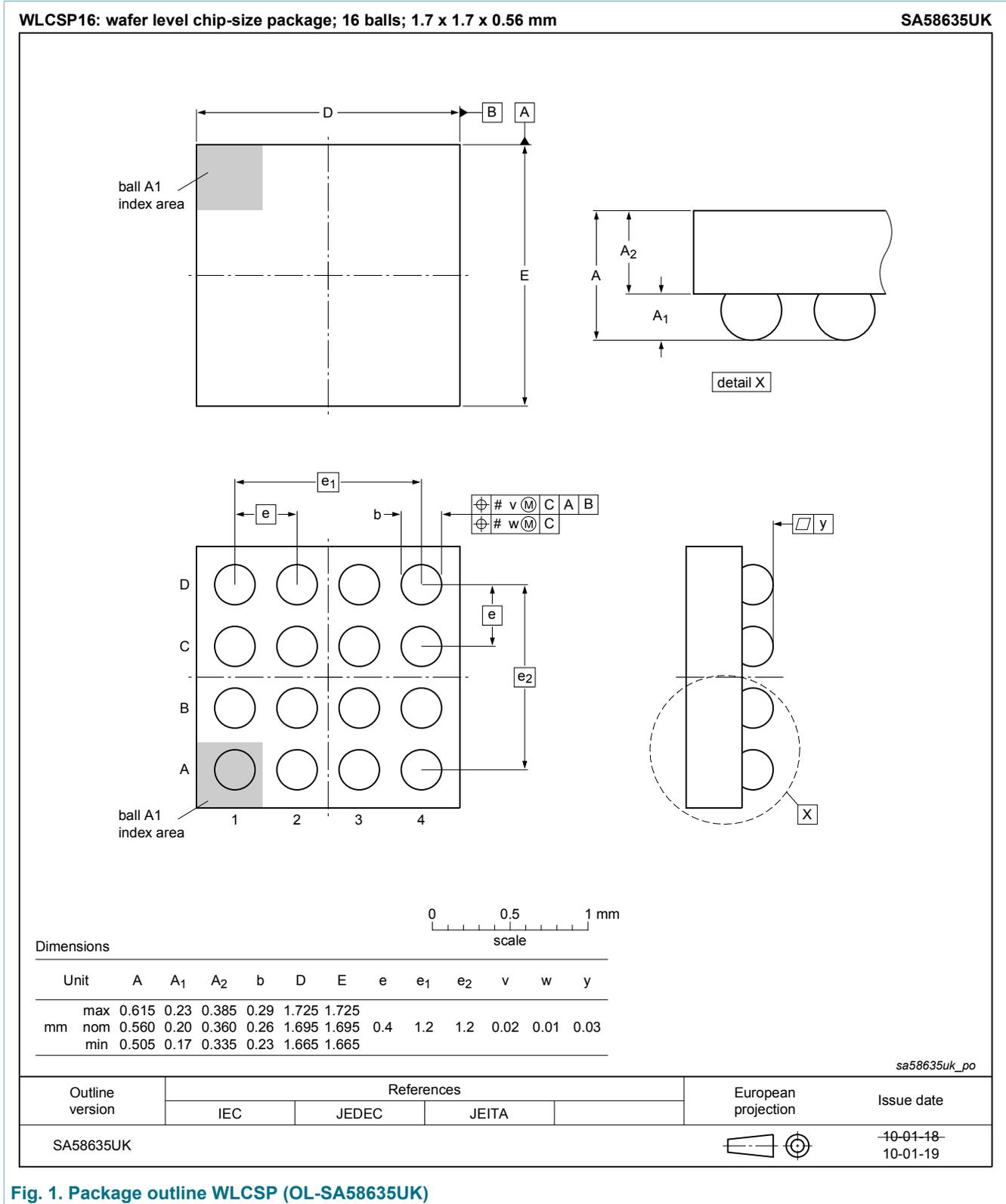


Fig. 1. Package outline WLCSP (OL-SA58635UK)

3. Legal information

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